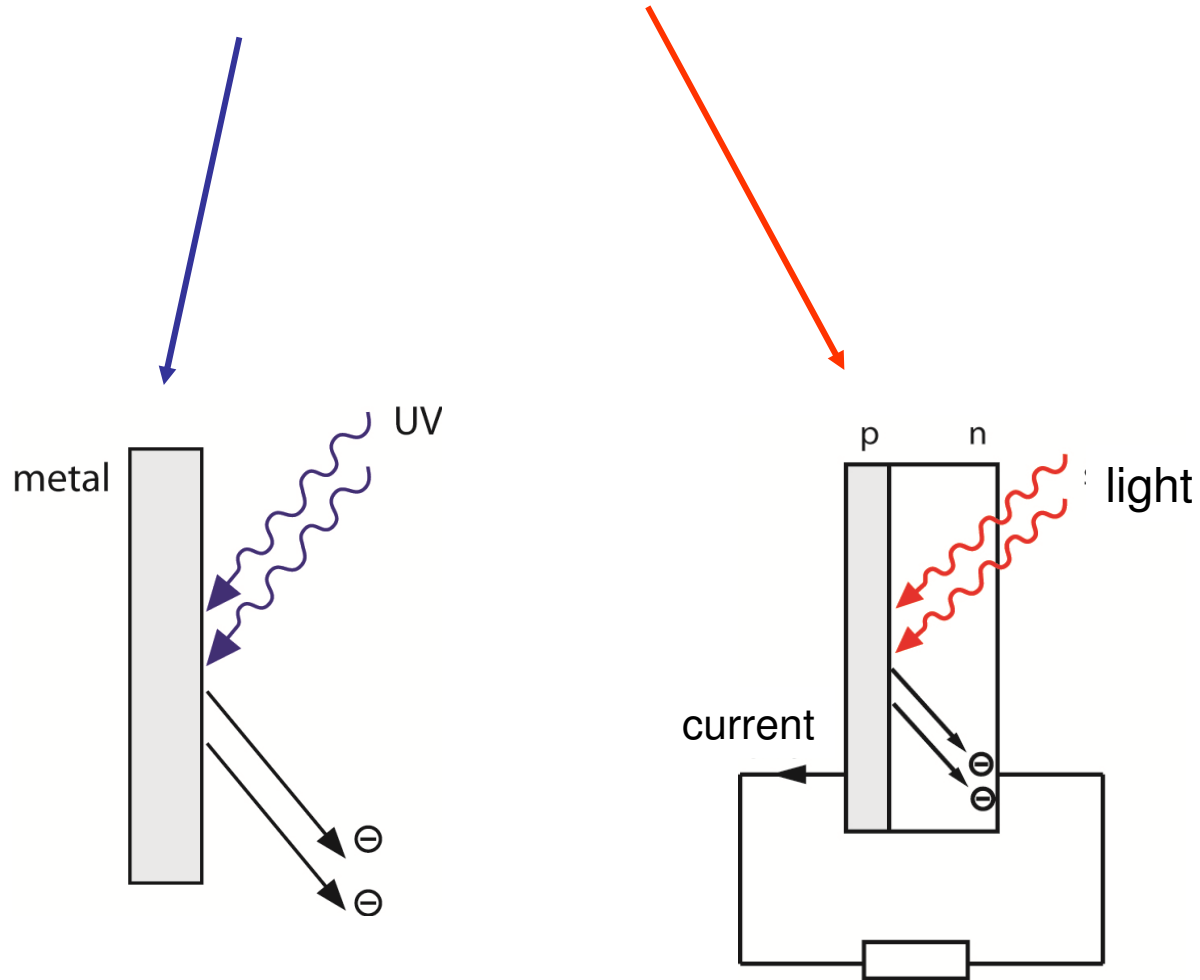
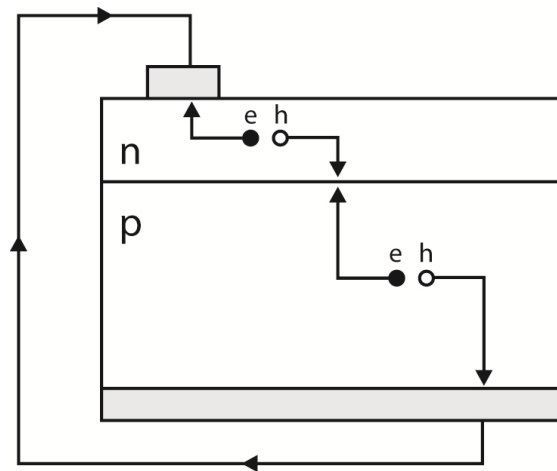
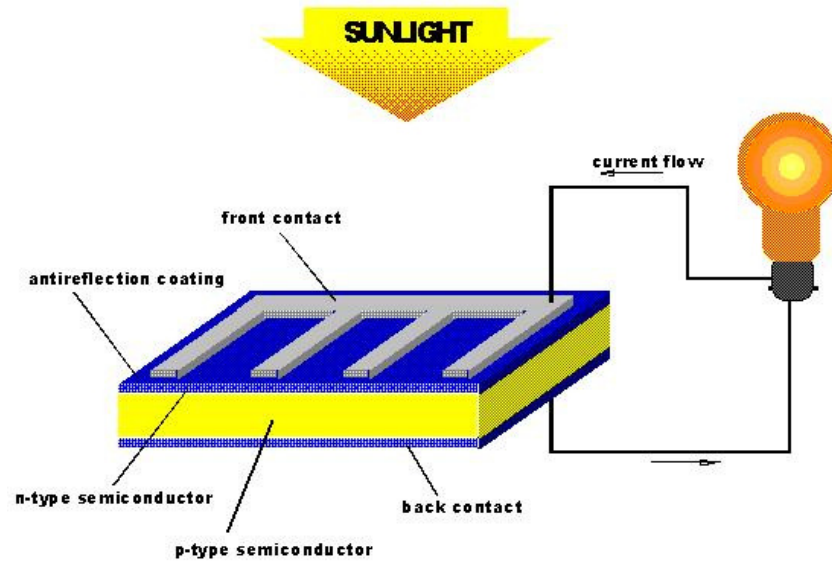


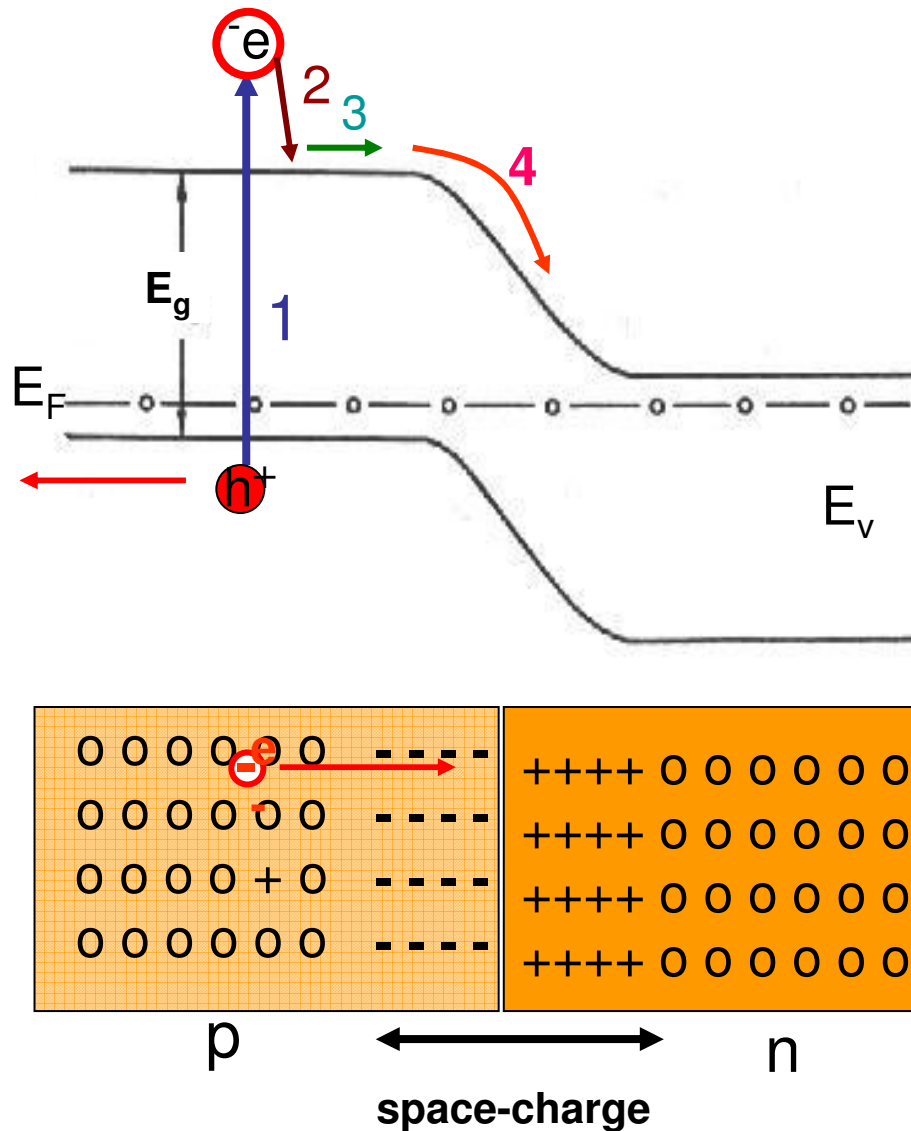
# External and internal photovoltaic effect



# Basic pn cell design



# Photovoltaic effect in pn junction



1. absorption
2. thermalisation
3. diffusion
4. drift

## important parameters:

- o band gap  $E_g$
- o doping level
- o absorption coefficient  $\alpha$
- o lifetime of carriers  $\tau$
- o diffusion length  $L_d$
- o mobility  $\mu$

# Current-voltage characteristics under illumination

## I-V in the dark

$$I_{\text{dark}} = J_o \left( \exp \left\{ \frac{eV}{Ak_B T} \right\} - 1 \right)$$

$$J_o = J_{o0} \exp \left\{ \frac{-E_a}{k_B T} \right\}$$

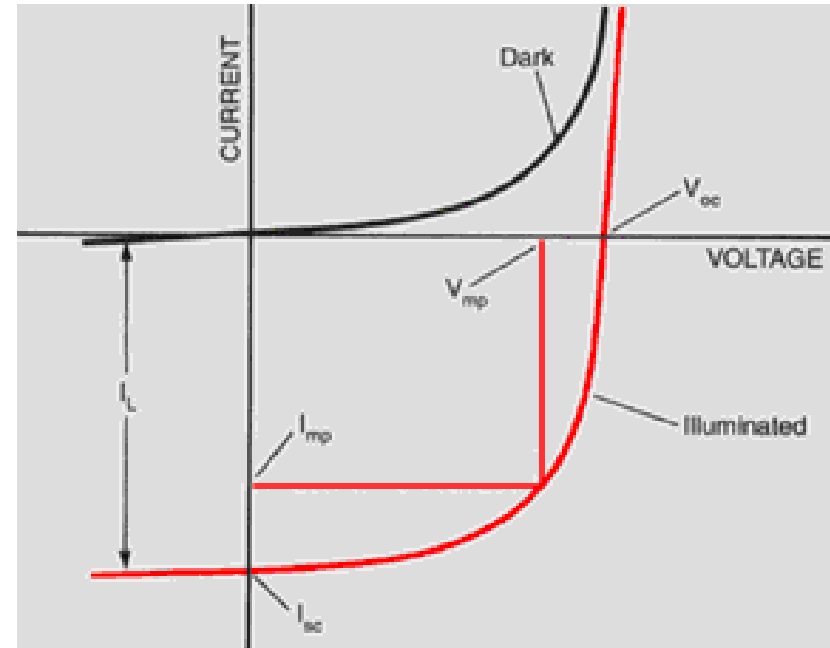
## I-V under illumination

*superposition principle:*

$$I_{\text{ill}} = I_{\text{dark}} - I_{\text{sc}}$$

$$I_{\text{ill}} = I_o \left( \exp \left\{ \frac{eV}{Ak_B T} \right\} - 1 \right) - I_{\text{sc}}$$

A – ideality factor,  $1 < A < 2$



# Efficiency

$$\eta = \frac{I_{mp} V_{mp}}{P_{in}} = \frac{I_{sc} V_{oc} FF}{P_{in}}$$

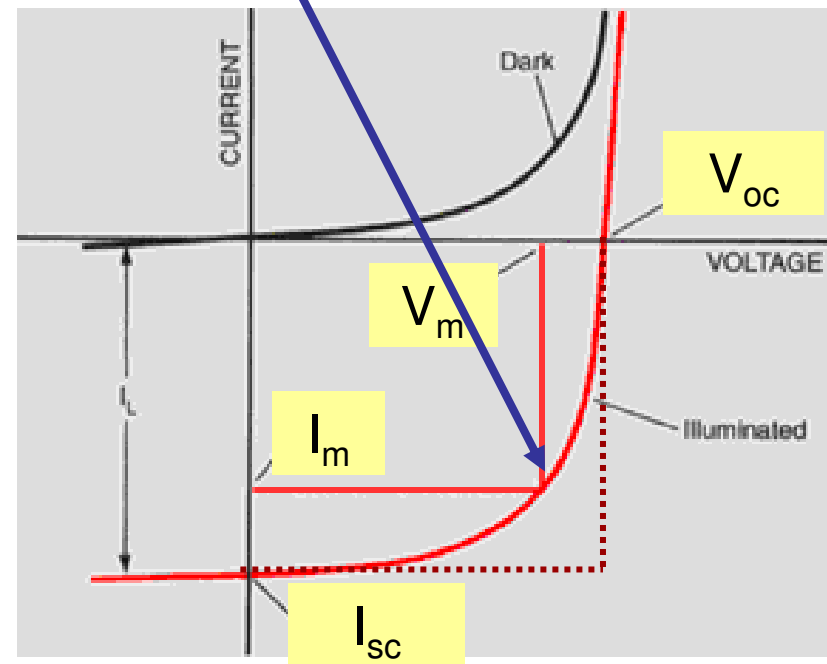
$I_{sc}$  – short circuit current:  
more absorbed photons - larger  $I_{sc}$

$V_{oc}$  – open circuit voltage  
*larger bandgap - higher  $V_{oc}$*

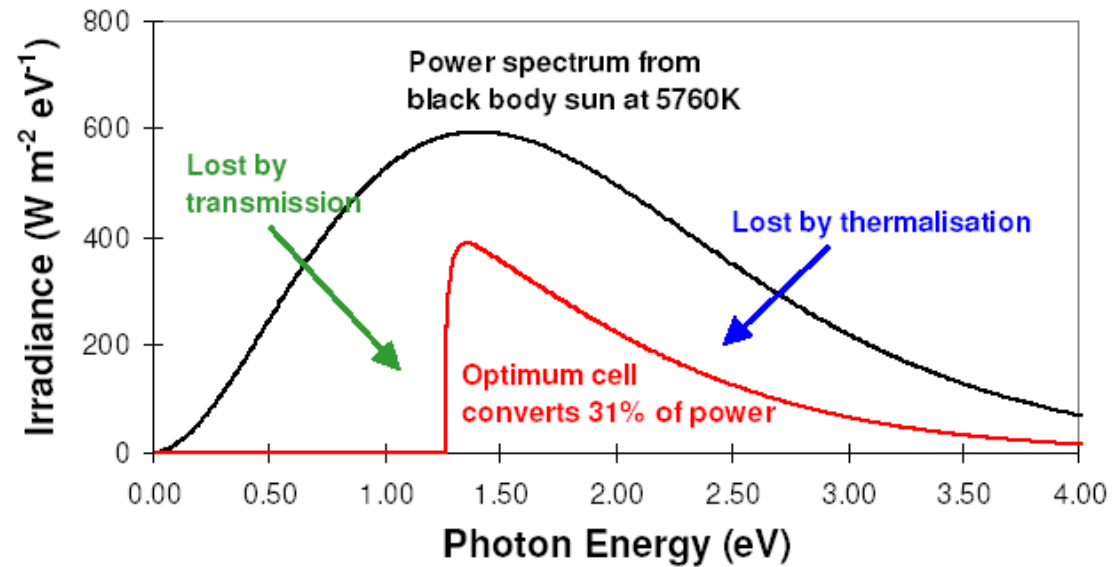
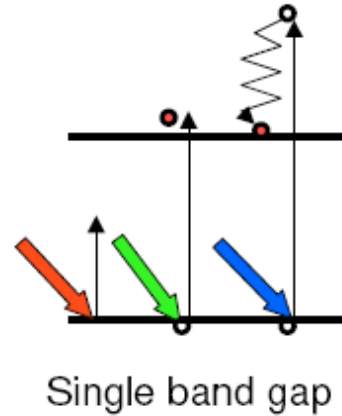
FF – fill factor

$$FF = \frac{I_{mp} V_{mp}}{I_{sc} V_{oc}}$$

maximum power  $I_m V_m$

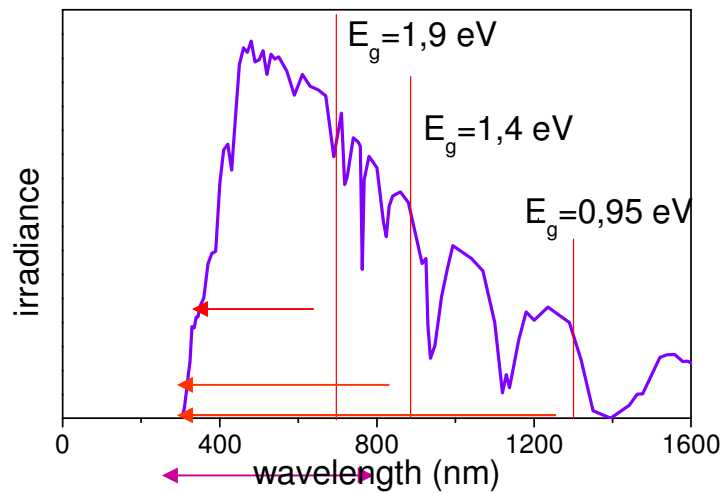


# Photogeneration and thermalisation

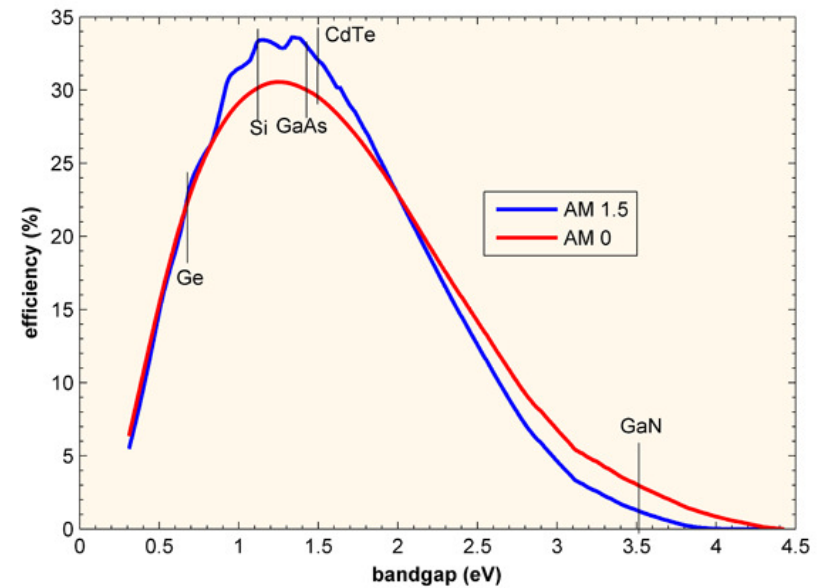


# Efficiency – dependence on $E_g$

solar spectrum AM1,5 (1 kW/m<sup>2</sup>)

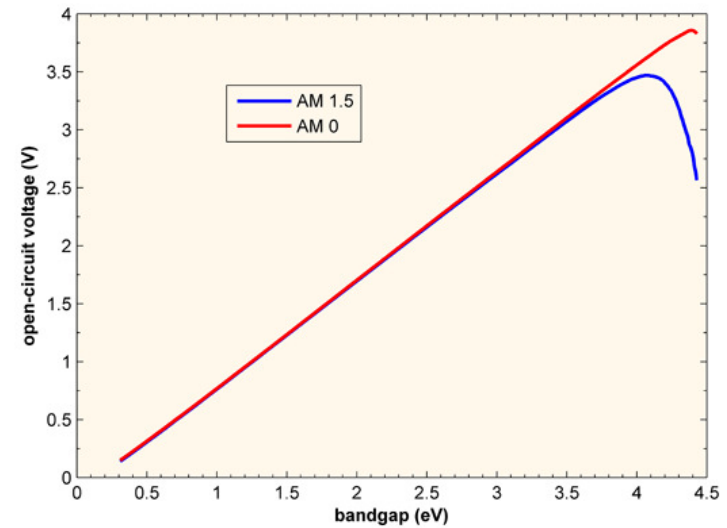
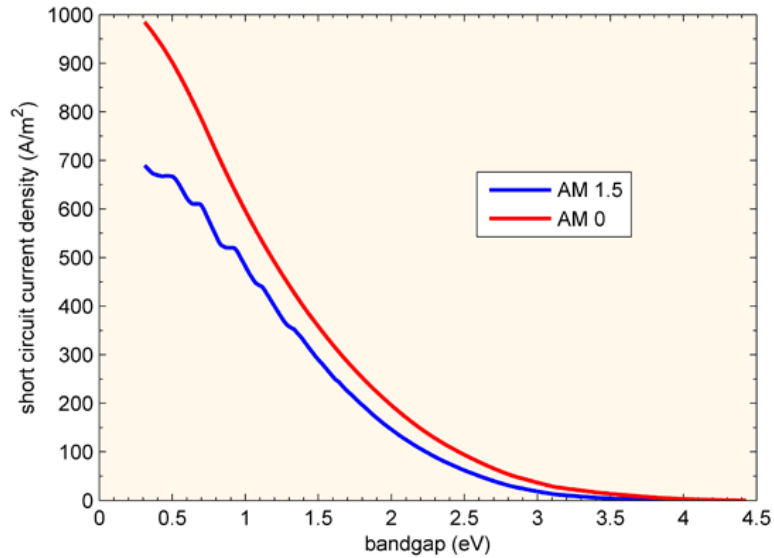


Maximum efficiency  
 $E_g = 1,4 - 1,5 \text{ eV}$



*max. possible efficiency for single junction (only radiative recombination, only thermalization losses, no other losses)*

# Maximum efficiency



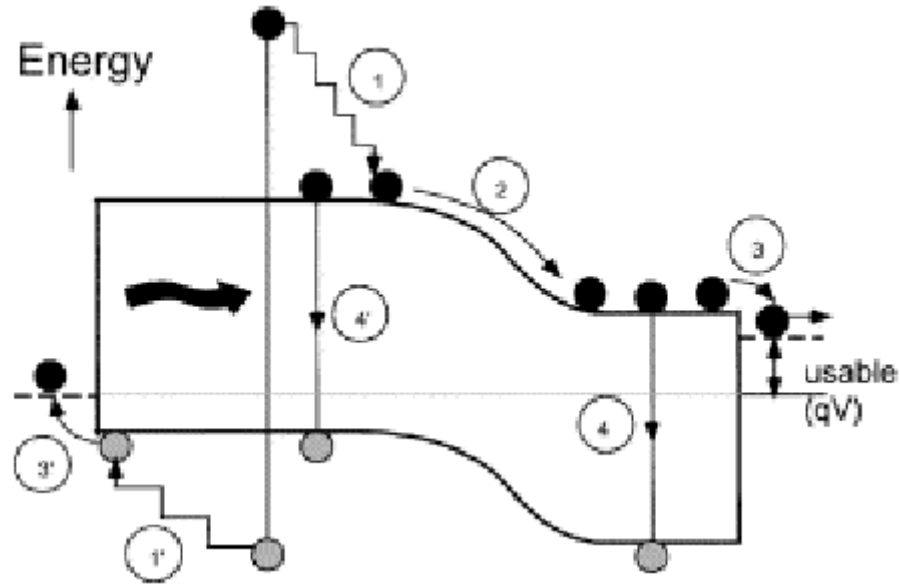
Isc  $\uparrow$  when  $E_g \downarrow$

Voc  $\uparrow$  when  $E_g \uparrow$

$\eta_{\max} : E_g \cong 1.5 \text{ eV}$



# Energy losses in the cell



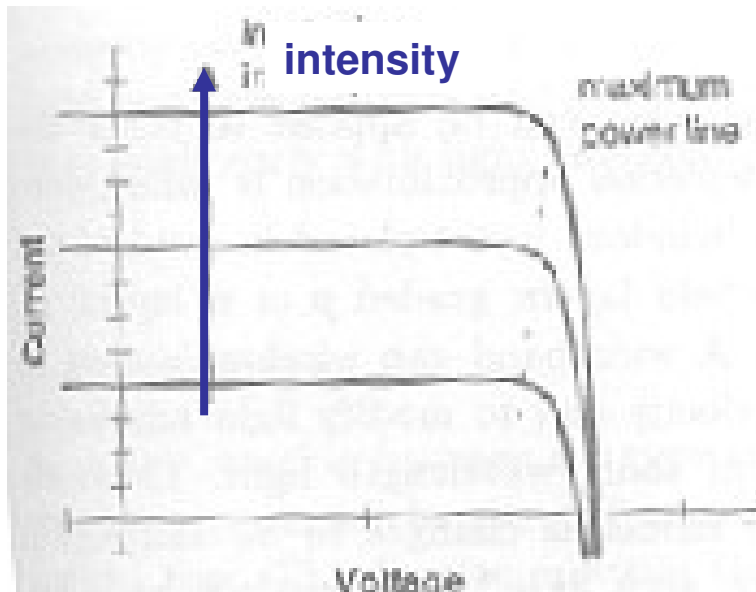
- (1) thermalisation loss;
- (2) junction loss;
- (3) contact loss;
- (4) recombination loss.

## Effect of light intensity

$$V_{oc} = \frac{Ak_B T}{e} \ln\left(\frac{I_{sc}}{I_o} + 1\right) \approx \frac{Ak_B T}{e} \ln\left(\frac{I_{sc}}{I_o}\right)$$

$$I_{sc} \sim \Phi \text{ (light intensity)}$$

$$V_{oc} \sim \ln \Phi$$



## Effect of temperature

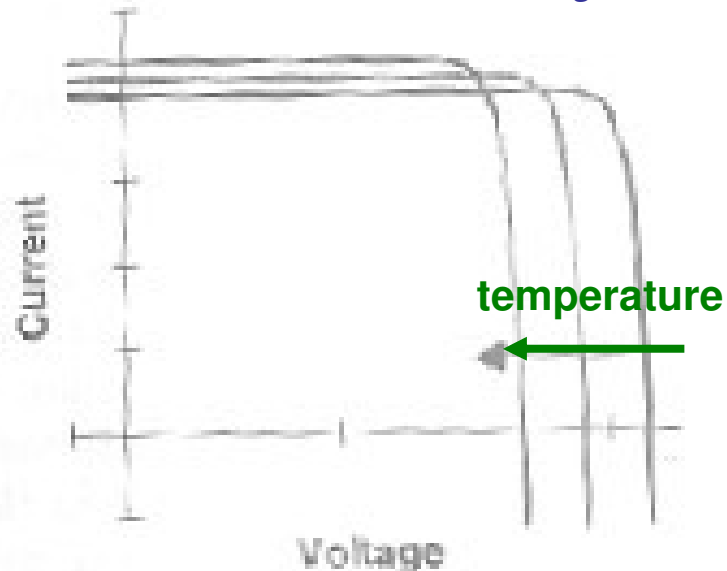
$$V_{oc} = \frac{Ak_B T}{e} \ln\left(\frac{I_{sc}}{I_o}\right) =$$

$$I_o = I_{oo} \exp\left\{\frac{-E_a}{k_B T}\right\}$$

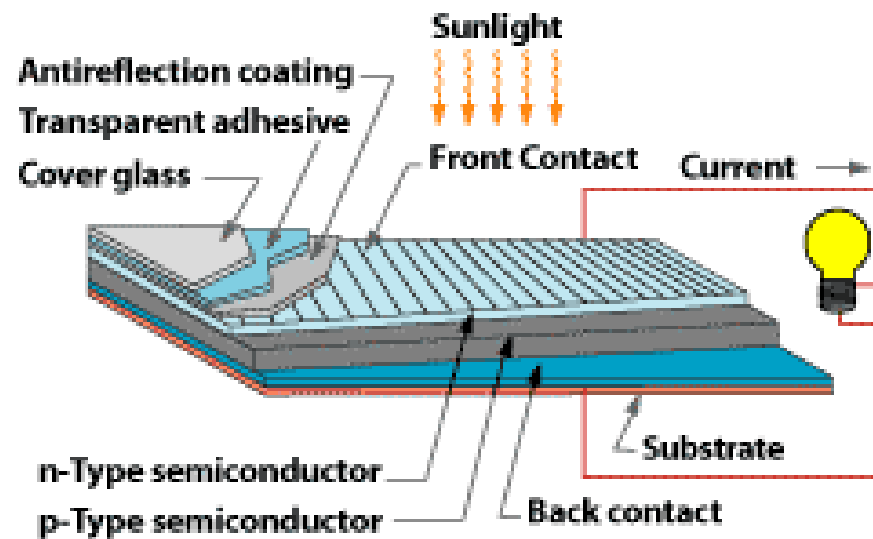
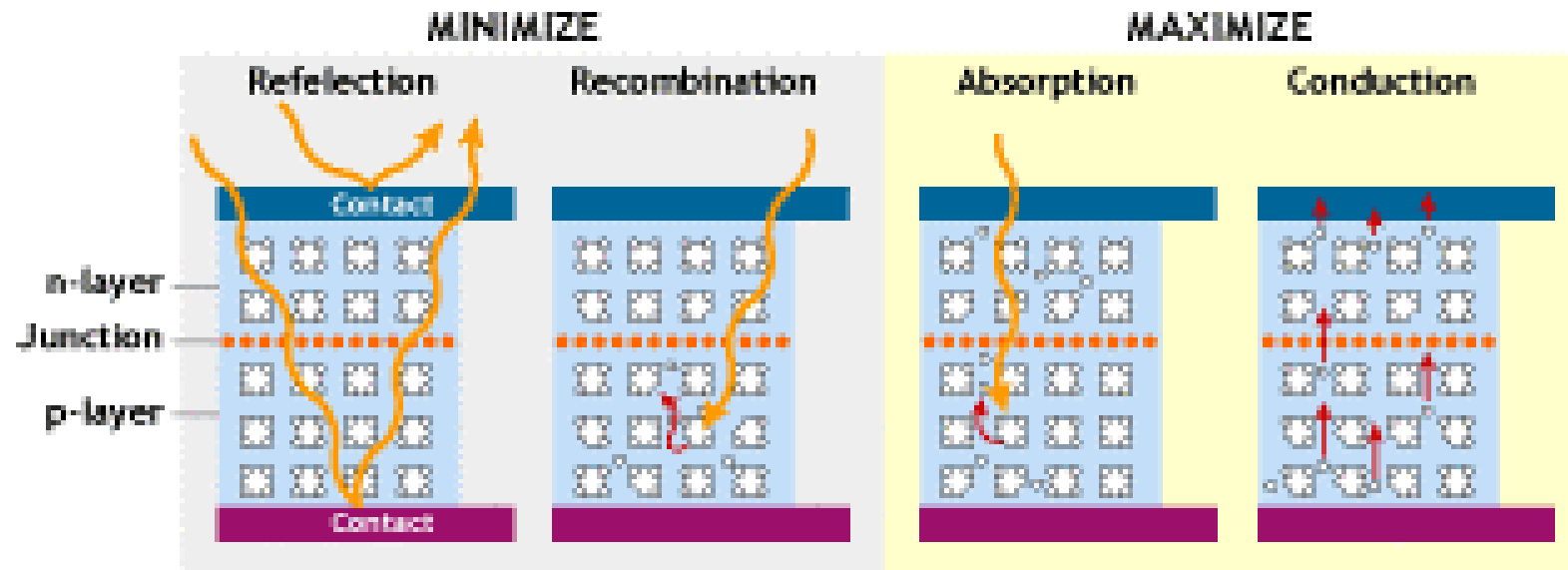
$$V_{oc} = \frac{AE_a}{e} - \frac{Ak_B T}{e} \ln \frac{I_{oo}}{I_{sc}}$$

$$I_{sc} \sim \text{const}$$

for pn junction  $E_a = E_g$ ,  $A=1$ ,

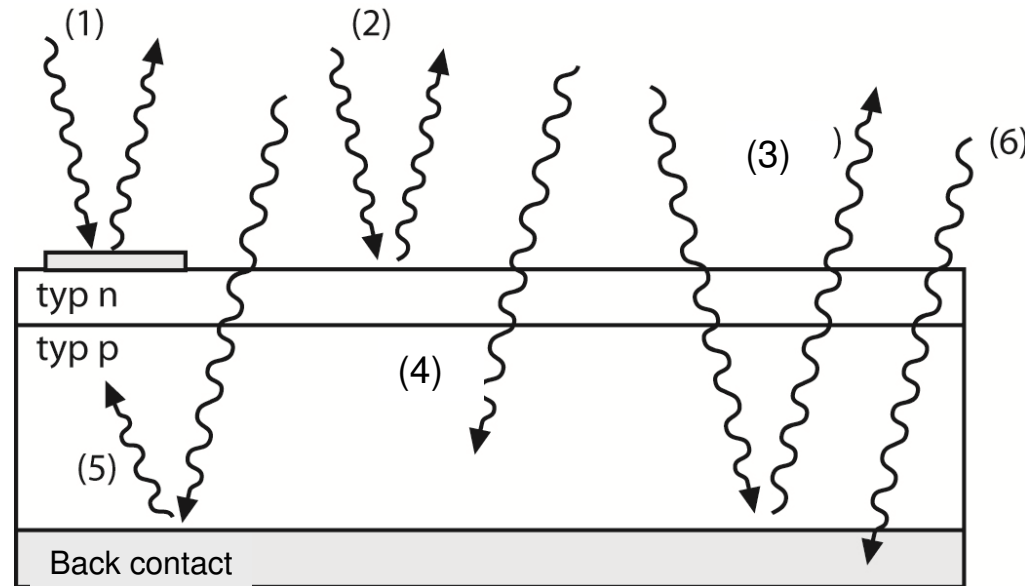


# Maximum efficiency if:



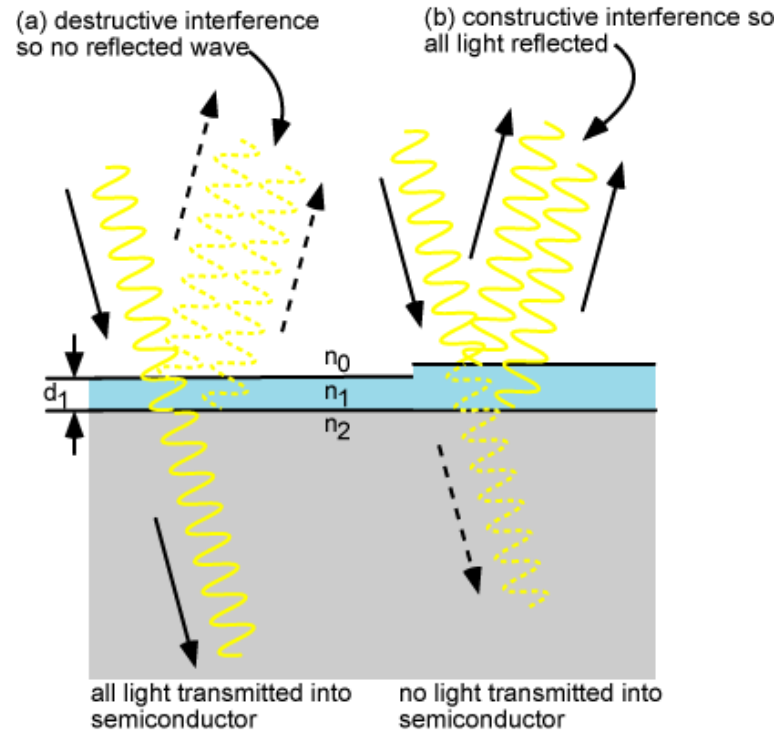
# Light in a cell

1. reflection at top contact
  2. reflection at cell surface
  3. reflection from the rear
  4. absorption
  5. absorption after reflection at rear contact
- losses**
- desired processes**



***light management: increase desired processes, decrease losses***

# Anti-reflection coating



$$d_1 = \frac{\lambda_0}{4n_1}$$

quarter wavelength antireflection coating  
- minimum reflection

$$n_1 = \sqrt{n_0 n_2}$$

optimal refractive index

# Reflection losses

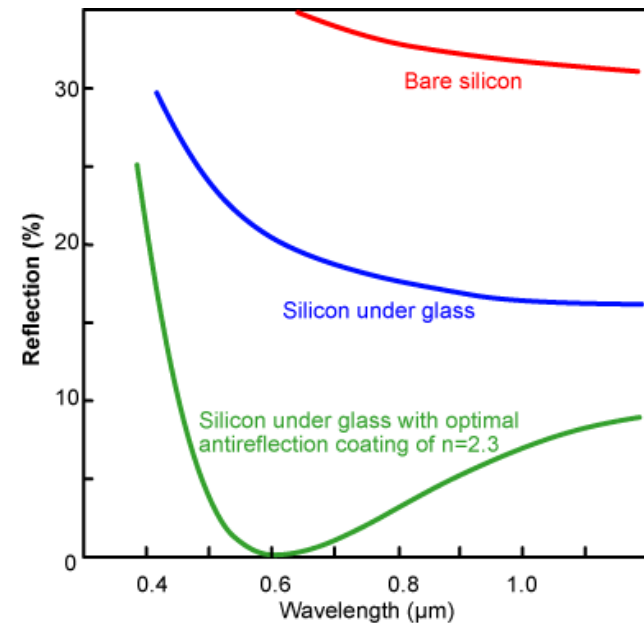
$$\Phi = \Phi_0(1-R)\exp\{-\alpha(\lambda) x\}$$

losses:  $R(\lambda)\phi_0(\lambda)\exp^{-\alpha(\lambda)x}$

- where
- $R(\lambda)$  - reflectivity of the Si
  - $\phi_0(\lambda)$  - photons incident on the surface
  - $\alpha(\lambda)$  - absorption coefficient of Si

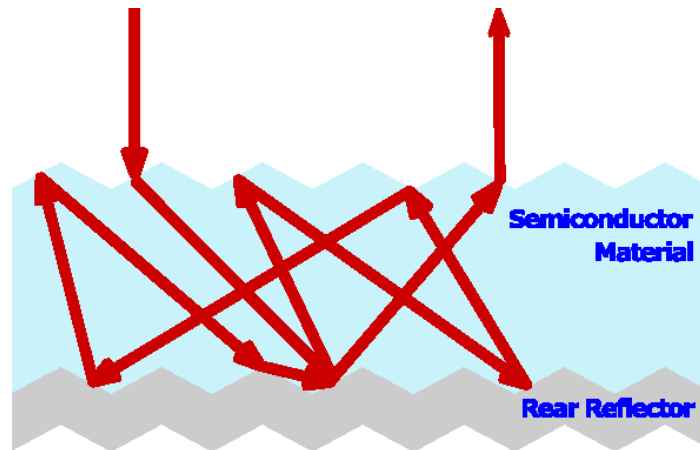
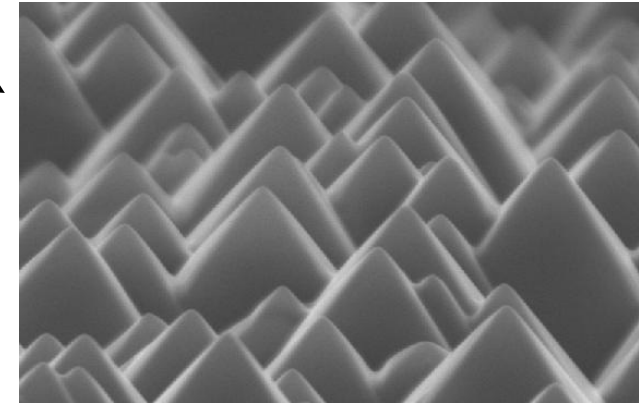
## to reduce the top surface reflection

- using an antireflective coating (SiO, SiN, MgF, ZnO)
- making the surface rough
- optimize top fingers design
- texturing (isotropic etching of the top surface)



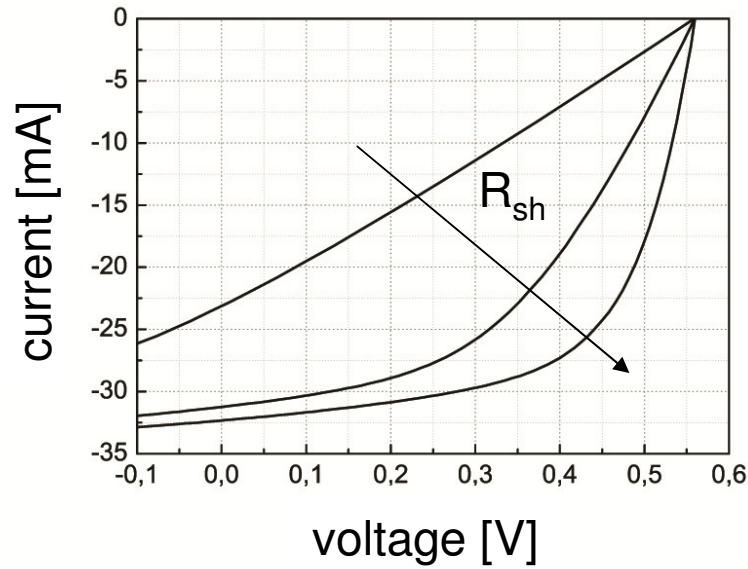
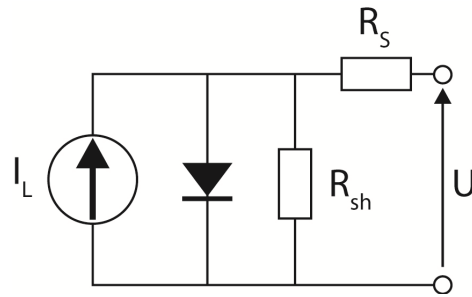
## Increase number of photons absorbed in the cell:

- reduce reflection
- increase photon path –light trapping (texture)
- optimize front electrode (buried contacts)

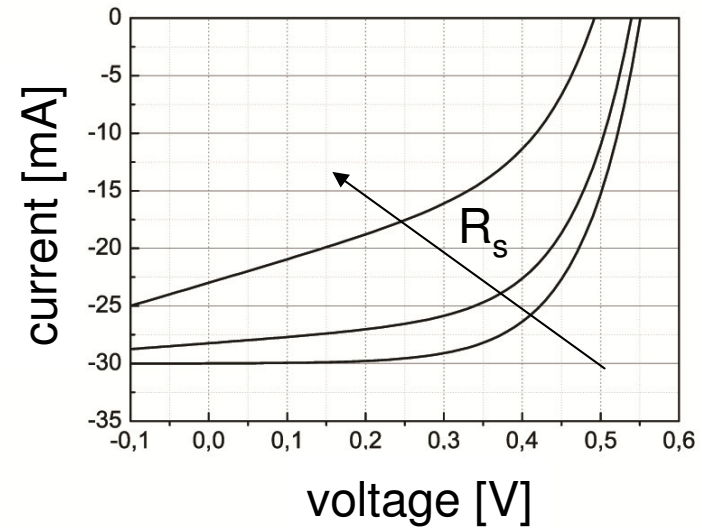


Front and rear surface texturing can trap light for multiple passes due to total internal reflection.

# Resistive losses



**shunt resistance**  
grains, edges, junction breakdown etc



**series resistance**  
*bulk absorber, contacts,  
electrical connections, etc* 16

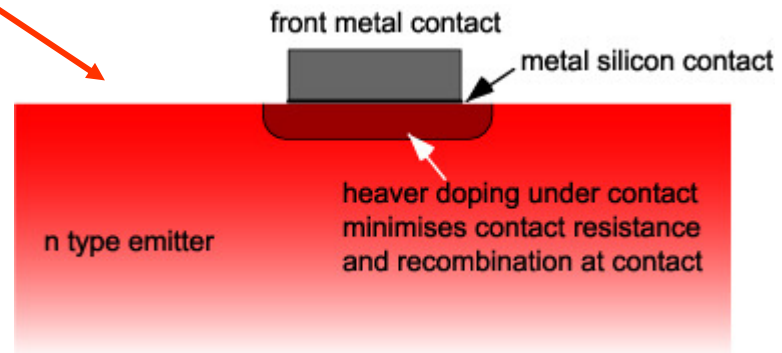
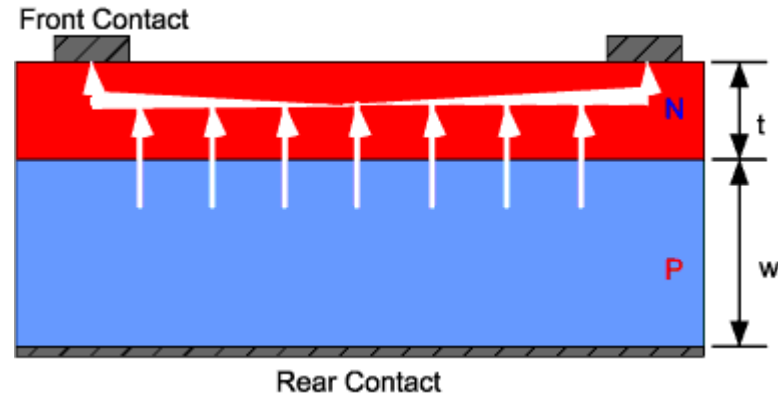


# Resistive losses

## Series resistance consists of

- ✓ bulk resistance
- ✓ emitter resistance
- ✓ metal-semiconductor contact resistance.
- ✓ fingers and bus bar resistance

*optimum busbar width:  
resistive loss = shadowing loss.*



# Effect of series and shunt resistance

effect on fill factor:

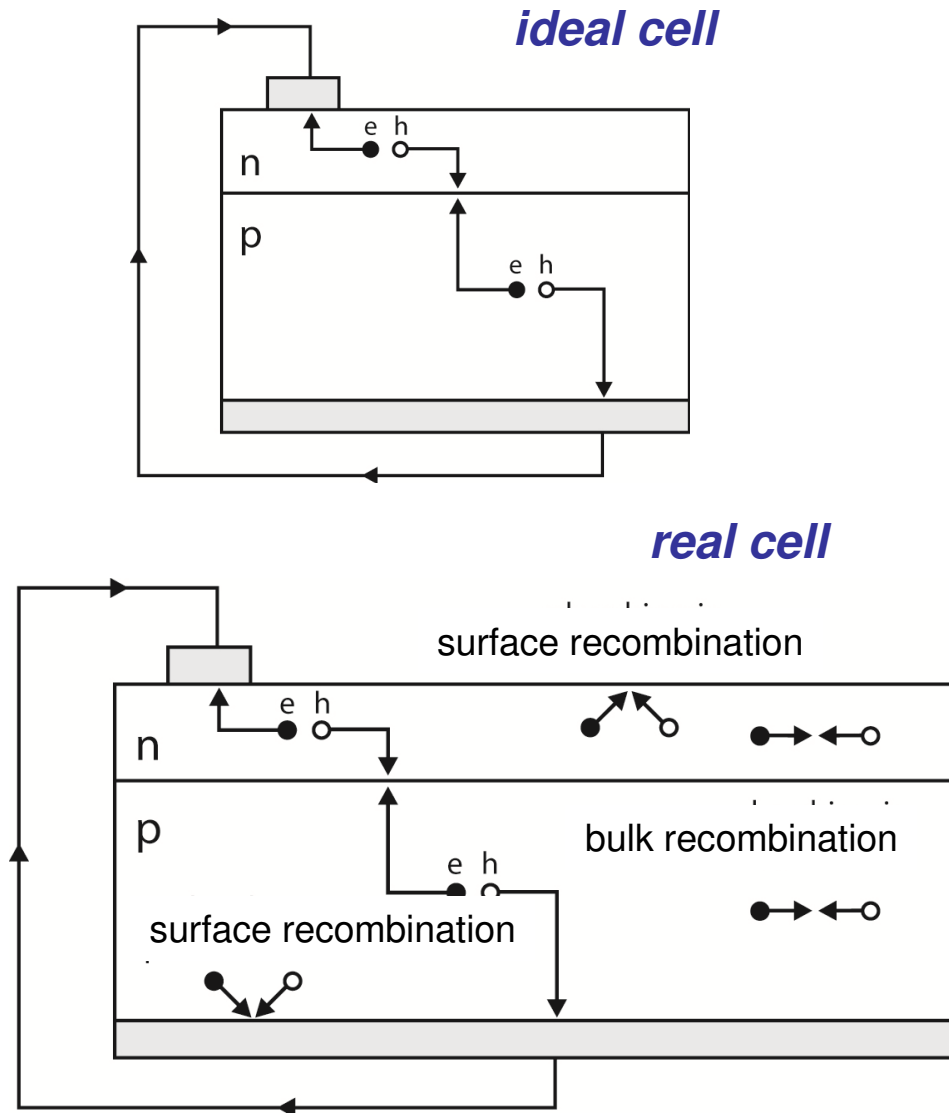
$$FF = FF_0(1 - r_s), \quad r_s = R_s / (V_{oc} / I_{sc})$$

$$FF = FF_0(1 - 1/r_{sh}), \quad r_{sh} = R_{sh} / (V_{oc} / I_{sc})$$

effect on illuminated current-voltage characteristics:

$$I_{ill} = I_o \left( \exp \left\{ \frac{e(V - R_s I)}{A k_B T} \right\} - 1 \right) + \frac{V - R_s I}{R_{sh}} - I_{sc}$$

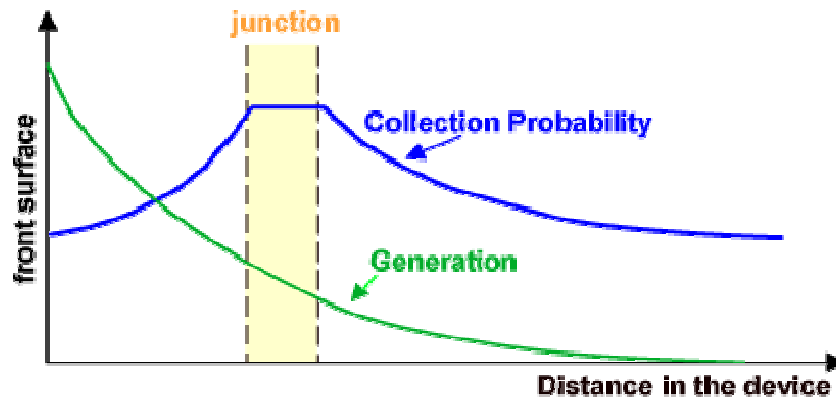
# Recombination losses contra collection



Type of recombination	Remedy
bulk recombination	high purity of bulk material
surface recombination	surface passivation (SiN, SiO)
recombination at metal –semi conductor contact	heavy doping of the contact region (BSF)

recombination losses – lifetime  $\tau$  of photoexcited carriers

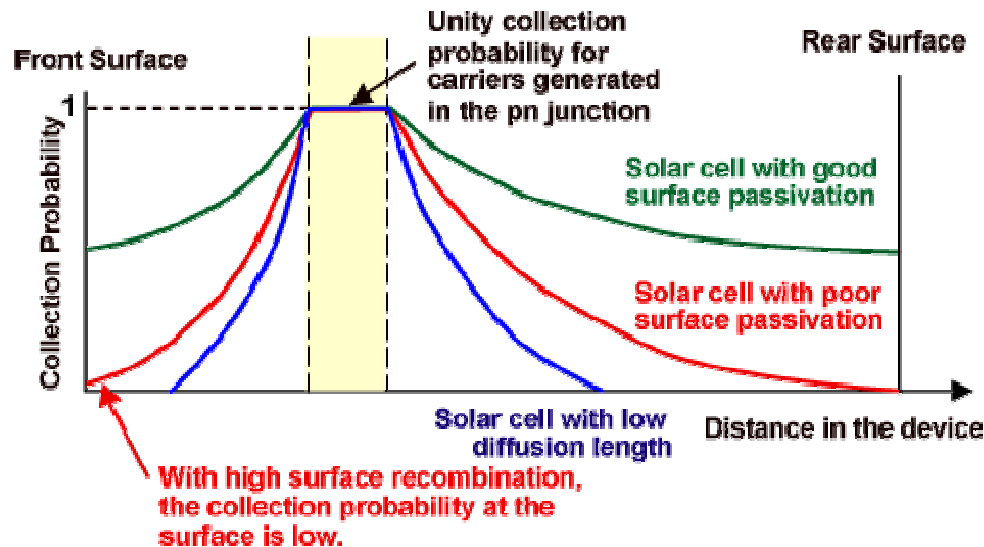
# Collection probability of photogenerated carriers



$W$  - thickness of the device;  
 $\alpha(\lambda)$  - absorption coefficient;  
 $H_0$  - number of photons at each wavelength

$$I_L = q \int_0^W G(x) CP(x) dx = q \int_0^W \left[ \int \alpha(\lambda) H_0 \exp(-\alpha(\lambda)x) d\lambda \right] CP(x) dx$$

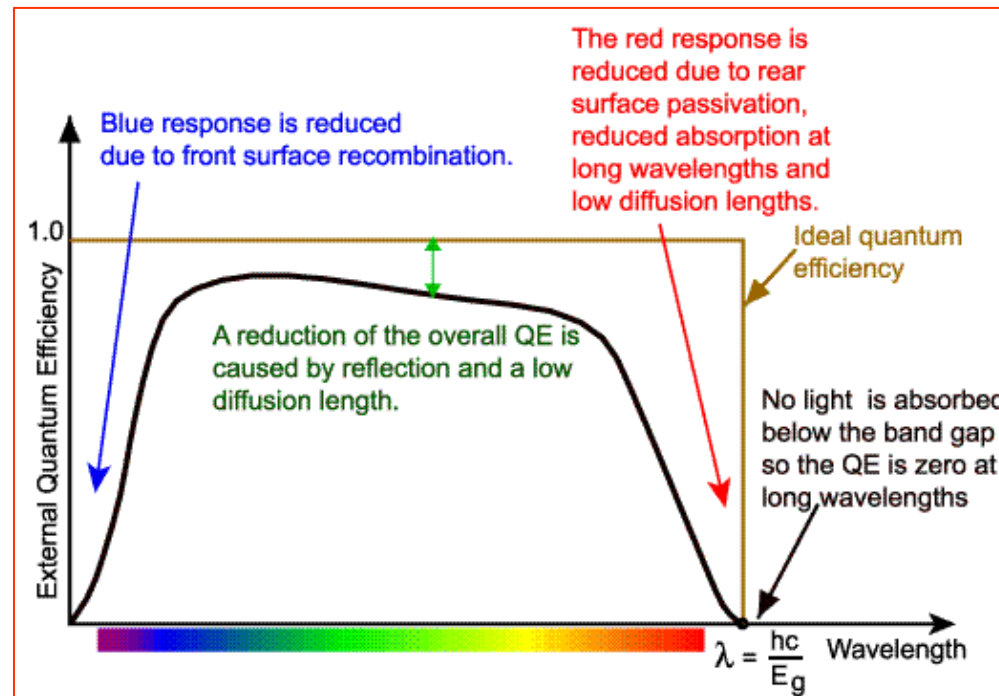
generation rate                      collection probability



# Quantum efficiency

*Ideal case: QE=1*     $QE = \frac{1 - \exp\{-\alpha W(U)\}}{1 + \alpha L_D}$

W - depletion width  
 $L_D$  - diffusion length



## Efficiency losses in a standard c-Si cell

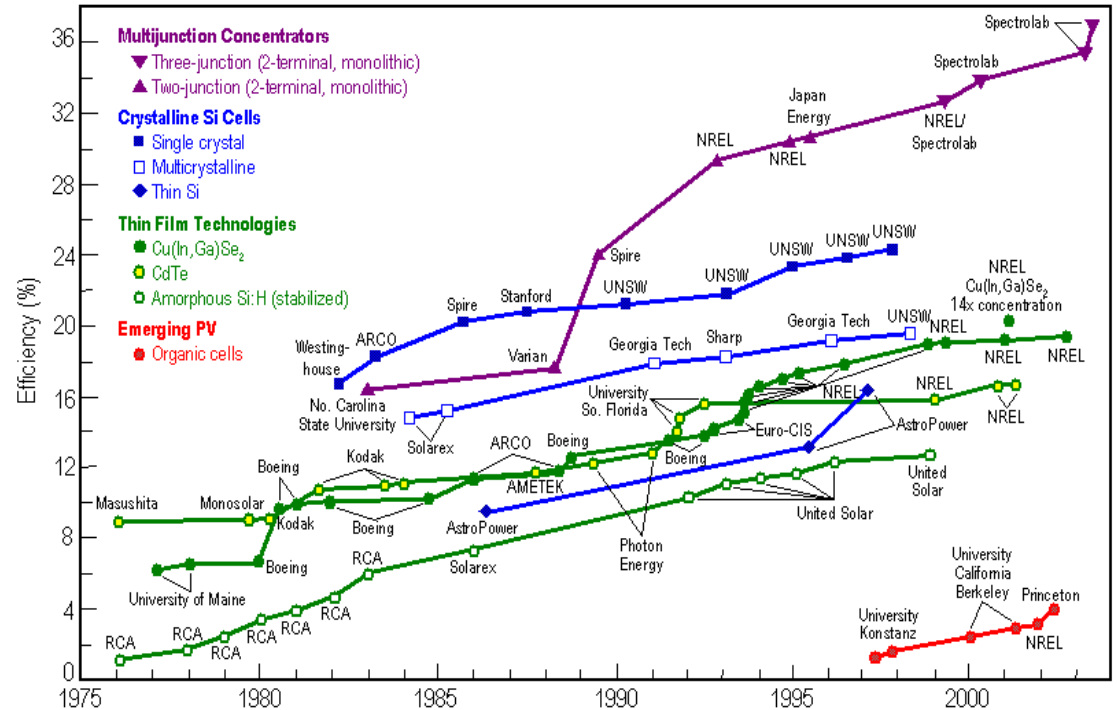
$$\eta = 16.6\%$$

grid coverage	4%
reflection loss	3%
$h\nu < E_g$	18.8%
$h\nu > E_g$	29.2%
collection loss (0.9)	4.5%
$qV_{oc} < E_g$	19.2%
FF=0.78	4.7%



# Best Research-Cell Efficiencies

[www.nrel.gov/ncpv/thin\\_film/docs/kaz\\_best\\_research\\_cells.ppt](http://www.nrel.gov/ncpv/thin_film/docs/kaz_best_research_cells.ppt)



	<i>Eff.</i> (%)	<i>Voc</i> (V)	<i>Jsc</i> (mA/cm <sup>2</sup> )	<i>FF</i> (%)
<b>Si-c</b>	24.7	0.706	42.2	82.8
<b>Si-μc</b>	19.8	0.654	38.1	79.5
<b>InP-c</b>	21.9	0.878	29.3	85.4
<b>a-Si (module)</b>	12.0	12.5	1.3	73.5
<b>GaAs (thin film)</b>	23.3	1.011	27.6	83.8
<b>CIGS</b>	18.4	0.669	35.7	77.0
<b>CIGS (module)</b>	16.6	2.643	8.35	75.1
<b>CdTe (cell)</b>	16.4	0.848	25.9	74.5
<b>CdTe (module)</b>	10.6	6.565	2.26	71.4
<b>Nanocr. dye</b>	6.5	0.769	13.4	63.0

Classification <sup>a</sup>	Effic. <sup>b</sup> (%)	Area <sup>c</sup> (cm <sup>2</sup> )	V <sub>oc</sub> <sup>d</sup> (V)	J <sub>sc</sub> <sup>d</sup> (mA/cm <sup>2</sup> )	FF <sup>d</sup> (%)	Test Centre <sup>e</sup> (and Date)	Description
<i>Silicon</i>							
Si (crystalline)	24.7 ± 0.5	4.00 (da)	0.706	42.2	82.8	Sandia (3/99)	UNSW PERL <sup>8</sup>
Si (multicrystalline)	20.3 ± 0.5	1.002 (ap)	0.664	37.7	80.9	NREL (3/04)	FinG-ISE <sup>10</sup>
Si (thin film transfer)	16.6 ± 0.4	4.017 (ap)	0.645	32.8	78.2	FinG-ISE (7/01)	U. Stuttgart (45 µm thick) <sup>11</sup>
<i>III-V Cells</i>							
GaAs (crystalline)	25.1 ± 0.8	3.91 (t)	1.022	26.2	87.1	NREL (3/90)	Kopin, AlGaAs window <sup>12</sup>
GaAs (thin film)	24.5 ± 0.5	1.002 (t)	1.029	28.8	82.5	FinG-ISE (5/05)	Radboud U., NL <sup>13</sup>
GaAs (multicrystalline)	18.2 ± 0.5	4.011 (t)	0.994	23.0	79.7	NREL (11/95)	RTL, Ge substrate <sup>14</sup>
InP (crystalline)	21.9 ± 0.7	4.02 (t)	0.878	29.3	85.4	NREL (4/90)	Spine, epitaxial <sup>15</sup>
<i>Thin film chalcogenide</i>							
CIGS (cell)	18.4 ± 0.5 <sup>f</sup>	1.04 (ap)	0.669	35.7	77.0	NREL (2/01)	NREL, CIGS on glass <sup>16</sup>
CIGS (submodule)	16.6 ± 0.4	16.0 (ap)	2.645	8.35	75.1	FinG-ISE (3/00)	U. Uppsala, 4 serial cells <sup>17</sup>
CdTe (cell)	16.5 ± 0.5 <sup>f</sup>	1.032 (ap)	0.645	25.9	75.5	NREL (9/01)	NREL, mesa on glass <sup>18</sup>
<i>Amorphous/</i>							
<i>nanocrystalline Si</i>							
Si (amorphous) <sup>g</sup>	9.5 ± 0.3	1.070 (ap)	0.850	17.5	63.0	NREL (4/03)	U. Neuchatel <sup>19</sup>
Si (nanocrystalline)	10.1 ± 0.2	1.199 (ap)	0.539	24.4	76.6	JQA (12/97)	Kaneka (2 µm on glass) <sup>20</sup>
<i>Photochemical</i>							
Nanocrystalline dye	10.4 ± 0.3	1.004 (ap)	0.729	21.8	45.2	AIST (8/05)	Sharp <sup>4</sup>
Nanocrystalline dye (submodule)	4.7 ± 0.2	14.14 (ap)	0.795	11.3	59.2	FinG-ISE (2/98)	INAP
<i>Multijunction devices</i>							
GaInP/GaAs/Cd-	32.0 ± 1.5	3.98 (t)	2.622	14.37	85.0	NREL (11/03)	Speerslab (monolithic)
GaInP/GaAs	30.3	4.0 (t)	2.488	14.22	85.6	JQA (4/96)	Japan Energy (monolithic) <sup>21</sup>
GaAs/CIS (thin film)	23.8 ± 1.3	4.00 (t)	—	—	—	NREL (11/89)	Kopin/Boeing (4 terminal)
a-Si/CIS (thin film) <sup>h</sup>	14.6 ± 0.7	2.40 (ap)	—	—	—	NREL (6/88)	ARCO (4 terminal) <sup>22</sup>
a-Si(a)-Si (thin submodule) <sup>i</sup>	11.7 ± 0.4	14.23 (ap)	5.462	2.99	71.3	AIST (9/04)	Kaneka (thin film) <sup>23</sup>

<sup>a</sup>CIGS = CuInGaSe<sub>2</sub>; a-Si = amorphous silicon/hydrogen alloy.

<sup>b</sup>Effic. = efficiency.

<sup>c</sup>(ap) = aperture area; (t) = total area; (da) = designated illumination area.

<sup>d</sup>FF = fill factor.

<sup>e</sup>FinG-ISE = Fraunhofer-Institut für Solare Energiesysteme; JQA = Japan Quality Assurance; AIST = Japanese National Institute of Advanced Industrial Science and Technology.

<sup>f</sup>Not measured in an external laboratory.

<sup>g</sup>Stabilised by 300h, 1-sun AM1.5 illumination at a cell temperature of 50°C.

<sup>h</sup>Unstabilised results.

<sup>i</sup>Stabilised by 174 h, 1-sun illumination after 20h, 5-sun illumination at a sample temperature of 50°C.



# Equations for solar cell operation

$$\frac{\partial \hat{E}}{\partial x} = \frac{\rho}{\varepsilon} = p + N_D^+ - n - N_A^- \quad \text{distribution of electric field}$$

$$J_n = q\mu_n n \hat{E} + qD_n \frac{dn}{dx}, \quad J_p = q\mu_p p \hat{E} + qD_p \frac{dp}{dx} \quad \text{current transport}$$

$$\frac{\partial n}{\partial t} = \frac{1}{q} \frac{\partial J_n}{\partial x} + G_n - U_n, \quad \frac{\partial p}{\partial t} = \frac{1}{q} \frac{\partial J_p}{\partial x} + G_p - U_p \quad \text{continuity equations}$$

$$G = \alpha N_s \exp(-\alpha x) \quad \text{carriers sec}^{-1} \text{ cm}^{-3} \quad \text{generation}$$

$$U_n = \frac{\Delta n}{\tau_n} \quad U_p = \frac{\Delta p}{\tau_p} \quad \text{recombination – bulk (Auger, radiative, SRH) and surface}$$